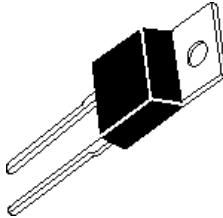
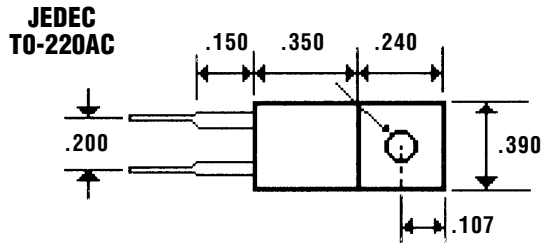


**FBR1650 & 1660**

## Description



## Mechanical Dimensions



## Features

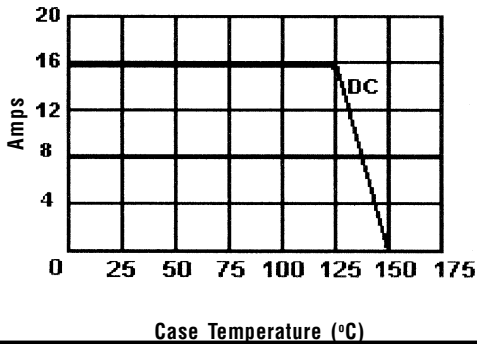
- HIGH CURRENT CAPABILITY WITH LOW  $V_F$
- HIGH SURGE VOLTAGE AND TRANSIENT PROTECTION
- HIGH EFFICIENCY w/LOW POWER LOSS
- MEETS UL SPECIFICATION 94V-0

Electrical Characteristics @ 25°C.	FBR1650 & 1660		Units
Maximum Ratings	FBR1650	FBR1660	
Peak Repetitive Reverse Voltage... $V_{RM}$	50	60	Volts
Working Peak Reverse Voltage... $V_{RWM}$	50	60	Volts
DC Blocking Voltage... $V_{DC}$	50	60	Volts
Average Forward Rectified Current... $I_{F(av)}$ @ $T_C = 125^\circ C$	16		Amps
Repetitive Peak Forward Surge Current... $I_{FM}$ $T_C = 125^\circ C$ (Rated $V_R$ , Square Wave, 20KHZ)	32		Amps
Non-Repetitive Peak Forward Surge Current... $I_{FSM}$ @ Rated Load Conditions, 8.3ms, 1/2 Sine Wave, Jedec Method	150		Amps
Repetitive Peak Reverse Surge Current... $I_{RSM}$ @ 2uS PW, F = 1.0 KHZ	0.5		Amps
Forward Voltage... $V_F$ Per Leg @ $I_F = 16$ Amps, 25°C	.75		Volts
Per Leg, 300uS, 2% Duty Cycle @ $I_F = 16$ Amps, 125°C	.65		Volts
DC Reverse Current (@ $V_R = V_{RM}$ )... $I_R$ @ Rated DC Blocking Voltage	1.0		mAmps
$T_C = 25^\circ C$	50		mAmps
$T_C = 125^\circ C$			
Thermal Resistance, Junction to Case... $R_{\theta JC}$	3.0		°C / W
Voltage Rate of Change (Rated $V_R$ )	1000		V / $\mu S$
Operating Temperature Range... $T_J$	-65 to 150		°C
Storage Temperature Range... $T_{STRG}$	-55 to 150		°C

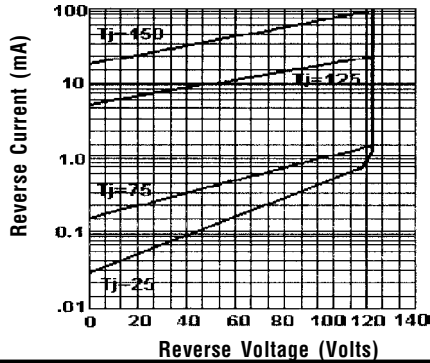
# 16 Amp SCHOTTKY BARRIER RECTIFIERS

**FBR1650 & 1660**

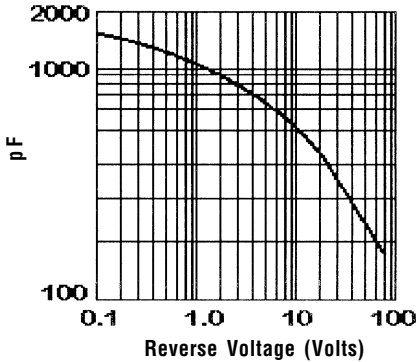
**Forward Current Derating Curve**



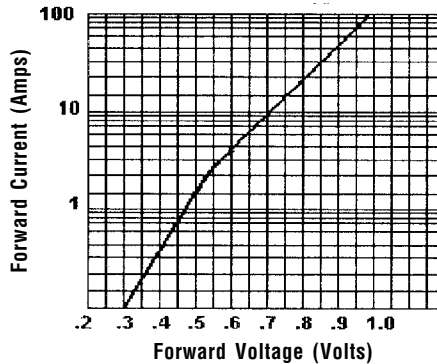
**Typical Reverse Characteristics**



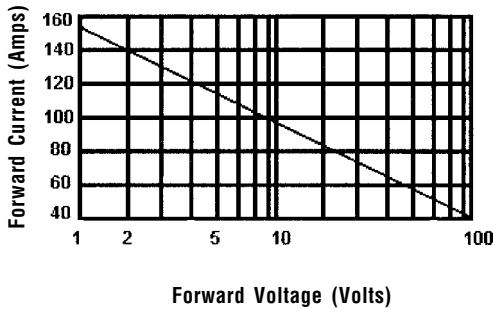
**Typical Junction Capacitance**



**Forward Characteristics**



**Maximum Non-Repetitive Peak Forward Surge Current**



**Case Positive, No Suffix Required**



Ratings at 25 Deg. C ambient temperature unless otherwise specified.

Single Phase Half Wave, 60 HZ Resistive or Inductive Load.

For Capacitive Load, Derate Current by 20%.

- NOTES:**
1. Measured @ 1 MHz and applied reverse voltage of 4.0V.
  2. Thermal Resistance Junction to Case, Jedec Method.
  3. When Mounted to heat sink, from body.